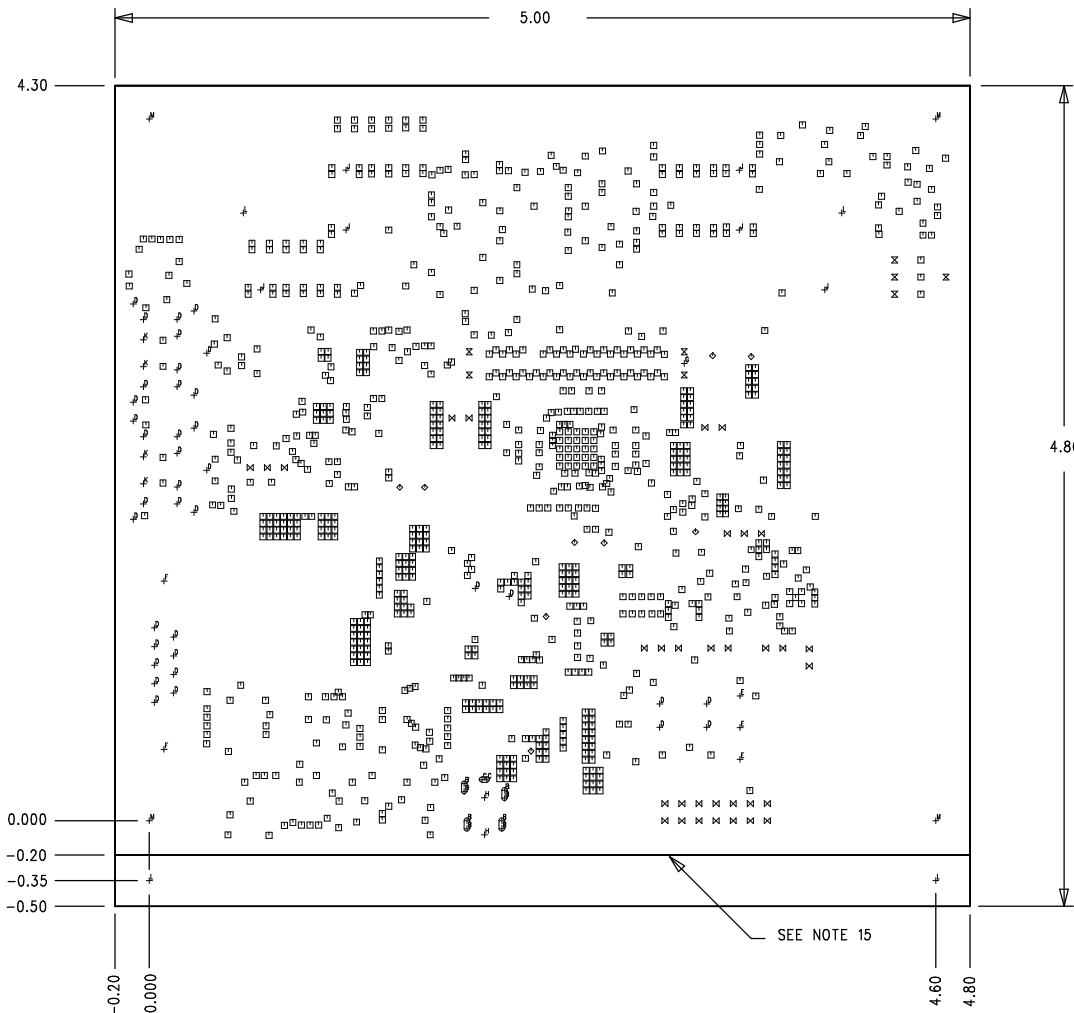


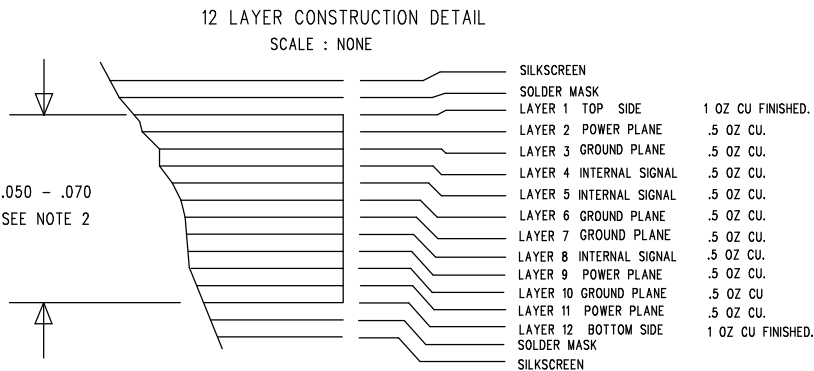
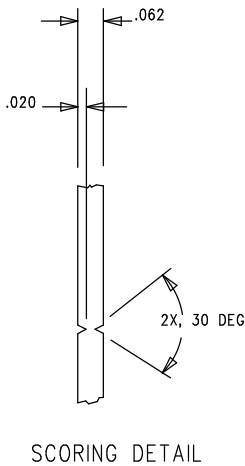
REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	ccd	1/6/11	




SIZE	QTY	SYM	PLATED	TOL
12	989	□	YES	+0.003/-0.012
28	9	◇	YES	+/-0.003
32 x 78	4	⊕ ^B	YES	+/-0.003
32	8	⊗	YES	+/-0.003
32 x 60	1	⊕ ^C	YES	+/-0.003
37	33	⊗	YES	+/-0.003
47	37	⊕ ^D	YES	+/-0.003
63	3	⊕ ^E	YES	+/-0.003
125	2	⊕ ^F	YES	+/-0.005
33	1	⊕ ^G	NO	+/-0.003
63	2	⊕ ^H	NO	+/-0.003
70	6	⊕ ^I	NO	+/-0.003
117	4	⊕ ^J	NO	+/-0.003
125	4	⊕ ^L	NO	+/-0.005
156	4	⊕ ^M	NO	+/-0.005

UNLESS OTHERWISE SPECIFIED

- BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
- MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU
INNER LAYERS 1/2 OZ/SQFT CU FINISHED .062 (.055 MIN .070 MAX SEE DETAIL).
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
- PLATING: ADDITIONAL CU PLATING 1/2 OZ/SQFT
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE
PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
- FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER
A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.
- SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
PHOTOPLOT FILES HAVE PAD SIZE SAME SIZE AS ETCHED PAD (1/1).
VENDOR MAY ADJUST SOLDERMASK PAD SIZE AS NEEDED.
- SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
- ARTWORK: MINIMUM FEATURE SIZE = 0.005
MINIMUM AIR GAP = 0.0049
- ALL DIMENSIONS ARE IN INCHES.
- CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE
OF 60 OHMS +/- 10% ON ALL .005" LINE WIDTHS
- THIEVING IS ALLOWED, UNLESS OTHERWISE SPECIFIED.
- VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1 IS PREFERRED.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE
FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION
GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS
LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
- VIA HOLES (.006, .010, .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
- TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
- USE IPC-D-356 NETLIST AS SUPPLIED FOR CHECKING.
THERE IS 1 INTENTIONAL SHORTS ON LAYER 1
GND AND PGND AT W1
PLEASE IGNORE THESE WHEN COMPARING THE IPC-356 NETLIST AND GERBERS.
CONTACT ANALOG DEVICES IF ANY OTHER DISCREPANCIES ARE FOUND.
- V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
- BUILD AS 1-UP PCB.



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN ccd	1/6/11	FABRICATION DRAWING ADSP-BF592 EZ-KIT LITE BOARD	
FINISH SEE NOTES	ENGINEERING CHECKED			
DO NOT SCALE THIS DRAWING	MANUFACTURING		SIZE B	REV. 0.1
		SCALE 1 : 1	SHEET 1 OF 1	